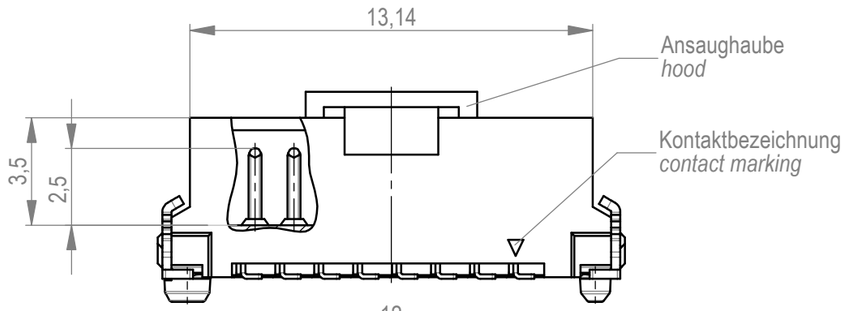
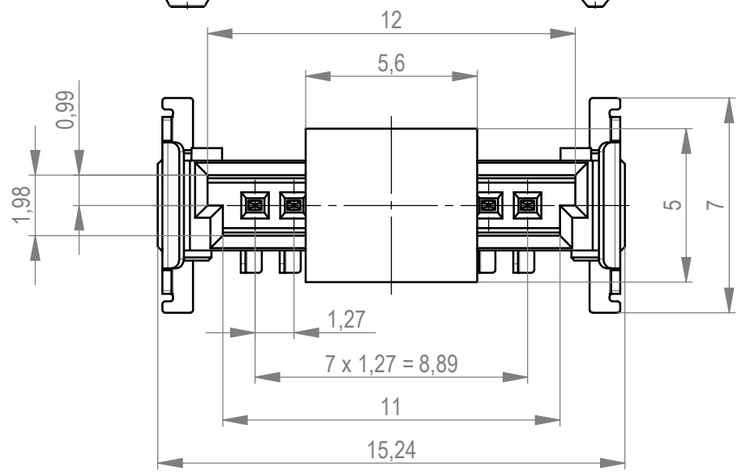
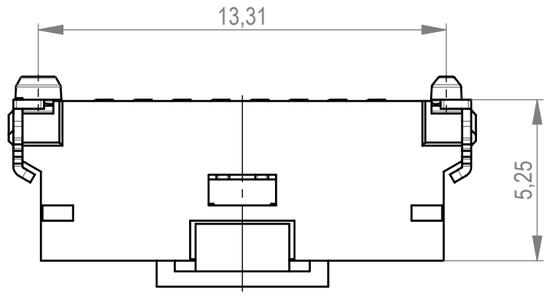
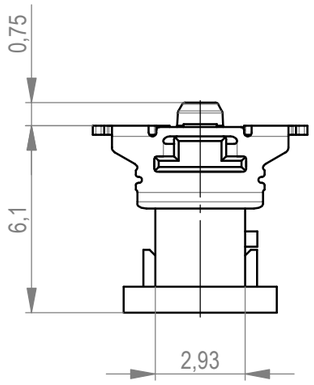
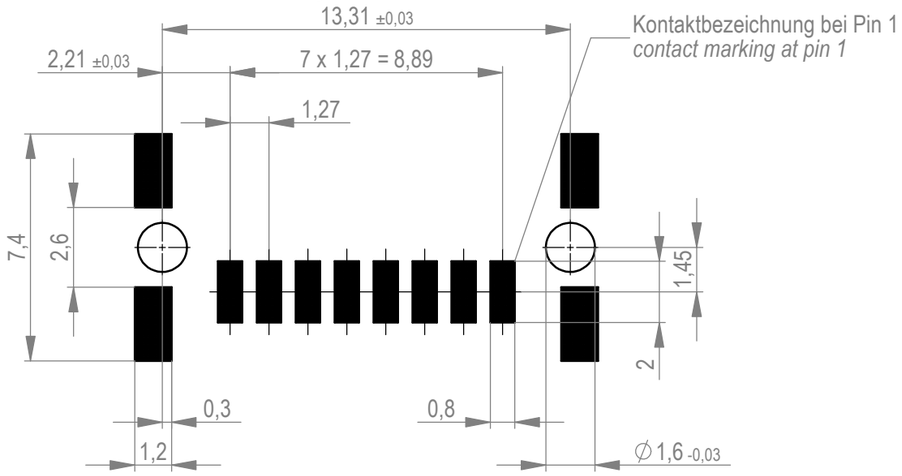




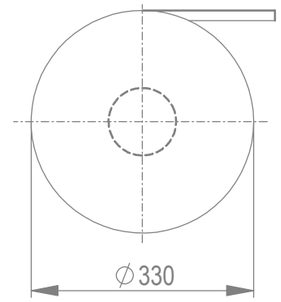




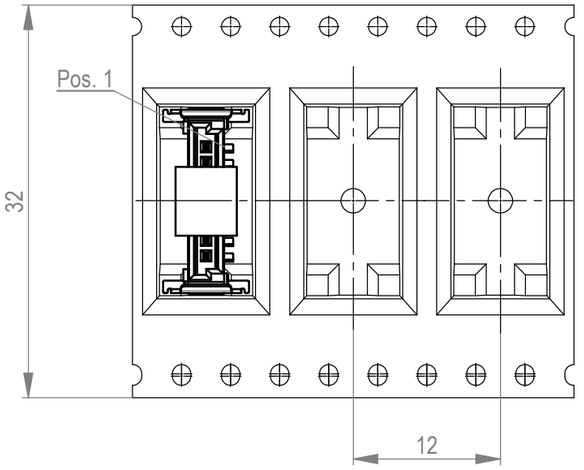
Leiterplatten-Layout für SMT
PCB-Layout for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 650 Stück
packaging unit: 650 pcs



Abspulrichtung - *reel off direction*



Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

*vergrösserte Lötpads
**enlarged solder pads*

Dimension no.	Tolerances Dim. for Information ISO 8015	All Dimensions in mm	Scale 5:1 Material
Customer drawing: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Subject to modification without prior notice. Drawing will not be updated.		MiniBridge Male Straight SMT 08p*
f / Index	01.03.2021 / Date	ERNI International AG Zürichstrasse 72 8306 Brüttisellen - Zürich Switzerland	284699 I A3 Class SRCP

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